2SK1625(L), 2SK1625(S)

Silicon N-Channel MOS FET

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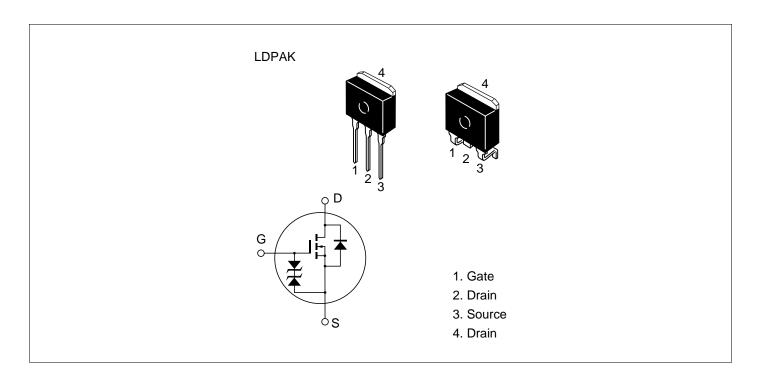
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





2SK1625(L), 2SK1625(S)

Absolute Maximum Ratings $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{\scriptscriptstyle DSS}$	600	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	7	A
Drain peak current	D(pulse) *1	28	A
Body to drain diode reverse drain current	I _{DR}	7	A
Channel dissipation	Pch*2	75	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_c = 25^{\circ}C$

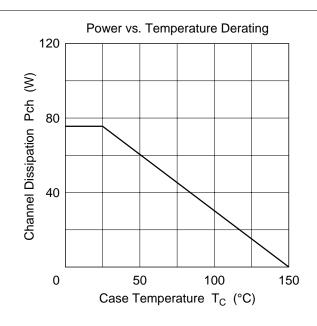
Electrical Characteristics (Ta = 25°C)

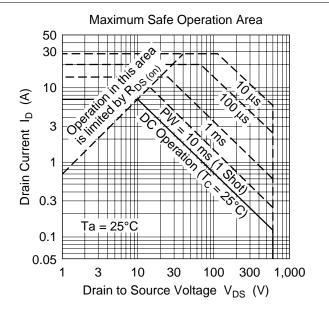
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	600	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	$I_{\rm GSS}$	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static Drain to source on state resistance	$R_{\mathrm{DS(on)}}$	_	0.9	1.3	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	yfs	4.0	6.5	_	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1180	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	265	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	50	_	pF	
Turn-on delay time	t _{d(on)}	_	15	_	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	50	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time	t _{d(off)}	_	105	_	ns	
Fall time	t _f	_	45		ns	
Body to drain diode forward voltage	V_{DF}	_	0.9	_	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	370	_	ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A/}\mu\text{s}$

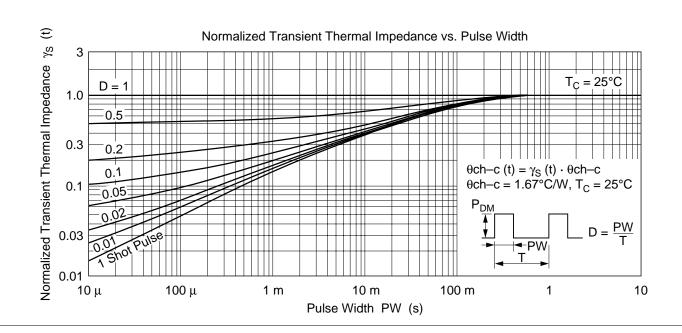
Note 1. Pulse test

See characteristic curves of 2SK1403.

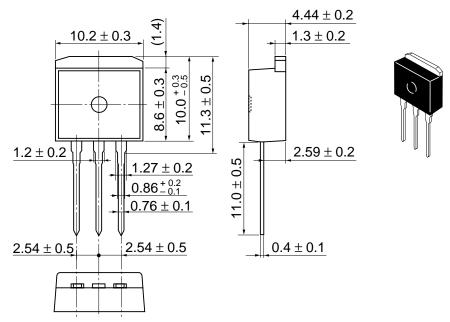
2SK1625(L), 2SK1625(S)







Unit: mm



Hitachi Code	LDPAK (L)
JEDEC	_
EIAJ	_
Weight (reference value)	1.4 g

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